

## UM-1 - Miniature Crystal

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Base	Board support	Fe	7439-89-6	0.643	0.39
	Board support	Cr	7440-47-3	0.156	0.09
	Board support	Ni	7440-02-0	0.069	0.04
	Centre support	Fe	7439-89-6	1.038	0.63
	Centre support	Cr	7440-47-3	0.482	0.29
	Centre support	Ni	7440-02-0	0.334	0.20
	Glass	SiO2 (Fibre Glass)	7631-86-9	3.226	1.96
	Glass	Al2O3	1344-28-1	0.323	0.20
	Glass	BaO	1304-2805	0.138	0.08
	Glass	B2O3	1303-86-2	0.922	0.56
	Ground Lead	Fe	7439-89-6	8.515	5.18
	Ground Lead	Ni	7440-02-0	4.573	2.78
	Ground Lead	Co	7440-48-4	2.681	1.63
	Header	Fe	7439-89-6	56.717	34.48
	Header	Ni	7440-02-0	30.459	18.52
	Header	Co	7440-48-4	17.855	10.85
	Lead	Fe	7439-89-6	18.913	11.50
	Lead	Ni	7440-02-0	10.157	6.17
	Lead	Co	7440-48-4	5.954	3.62
	Plated Au	Au	7440-57-5	0.344	0.21
	Plated Ni	Ni	7440-02-0	0.899	0.55
	Plated Ni	P	7723-14-0	0.089	0.05
	Cap	Cap	Ni	7440-02-0	43.200
Cap		Cu	7440-50-8	172.800	79.44
Plated Ni		Ni	7440-02-0	1.380	0.63
Plated Ni		P	7723-14-0	0.150	0.07
Crystal	Crystal	SiO2	14808-60-7	2.230	83.21
	Crystal Adhesive	Ag	7440-22-4	0.366	13.66
	Crystal Adhesive	Epoxy	129915-35-1	0.061	2.28
	Crystal Electrode	Ag	7440-22-4	0.023	0.86
	Crystal Electrode	Ni	7440-02-0	0.000	0.00
<b>Total Mass:</b>				<b>384.697 mg</b>	



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